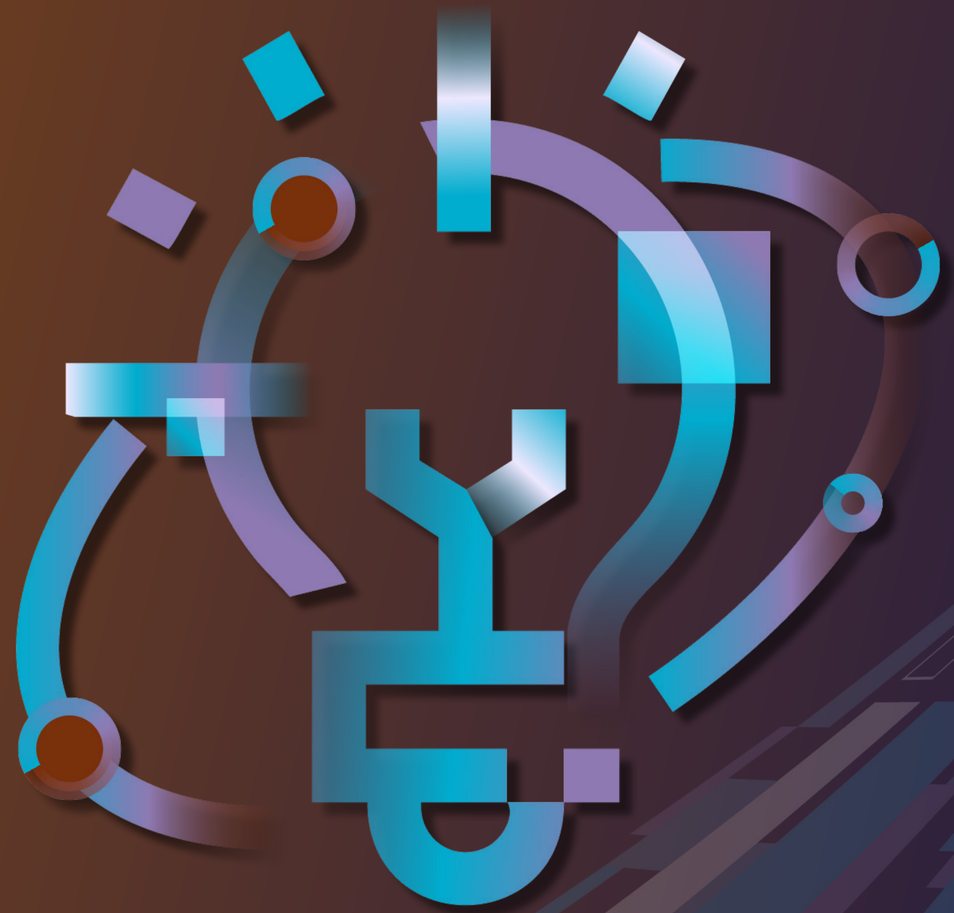
1 Value Co-Creation

1.1 About Fitipower

1.2 Product and Technology Innovation



Corresponding Stakeholders and Material Topics

Employee

Customer

Academic Institution

Association

R&D Innovation and Intellectual Property Management

Green Products

Policy and Response to SDGs

Adhering to sustainable operations, by innovating management, marketing, and technology, we constantly enhance market competitiveness, provide new and high-tech products and services integrating social wellbeing and environmental protection to realize our brand vision: Drive your heart, Power your life.

1.1 About Fitipower

Fitipower Group specializes in IC design and semiconductor technology innovation, encompassing Fitipower Integrated Technology Inc. and JADARD TECHNOLOGY INC., jointly committed to developing key chips for panel displays, power management, mobile intelligent terminals, and IoT applications. Fitipower Integrated Technology was established in 1995 with headquarters in Hsinchu, Taiwan, and listed on the Taiwan Stock Exchange in 2018 (TWSE: 4961). We possess sophisticated analog, digital, and mixed-signal R&D capabilities, with core products and services including comprehensive solutions for display driver ICs and power management ICs, along with various chip products such as timing controller ICs and motor driver ICs. JADARD (SSE: 688252) focuses on key chips for mobile intelligent terminals and smart IoT applications. Its products encompass display driver ICs (including touch and display driver integration), camera voice coil motor chips, fast charging protocol chips, and electronic label driver chips. Through continuous research, development, improvement, and validation, our products have gained the favor of customers worldwide. Export sales account for nearly 90% of our business, with the core market concentrated in Asia. Beyond our Hsinchu headquarters, we maintain operational bases in Neihu (Taipei), Tainan, and Shenzhen, China, providing customers with real-time technical services and business support. Looking forward, Fitipower Group will continue deepening R&D and technological innovation, advancing high-performance chip solutions to address global semiconductor industry transformation and market demands. Through steady operations and global deployment, the Group is committed to becoming a world-class IC design leader, providing customers with superior products and services.

Our official website incorporates comprehensive architecture and diverse interactive functions, including multimedia sections, surveys, and product inquiry forms, enabling stakeholders to more conveniently access needed information and directly interact with us. Website content covers the Company's vision and mission, development strategies and policies, products and services, talent recruitment and benefits, and ESG-related information to enhance corporate transparency and digital communication efficiency.

Fitipower Website | Fitipower Foundation Website | JADARD Website

Name	Fitipower Integrated Technology Inc.
Date Established	1995
Company Type	Publicly listed company (TWSE: 4961)
Main Business	Professional driver IC and power management IC design integration services
Headquarters	3F., No. 6-8, Duxing Rd., Hsinchu Science Park, Hsinchu City, Taiwan (R.O.C.)
Chairman	Mr. Young Lin
President	Ms. Sophia Chiu
Paid-in Capital	NT$1.213 billion (2024/12/31)
Revenue	NT$19.199 billion (2024)
Number of Employees	842 people (2024/12/31)

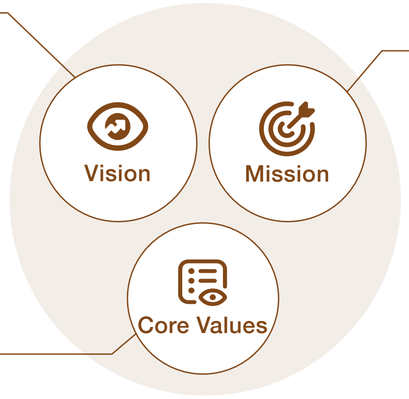
Our Vision and Mission

Leading Smart Living · Driving the Carbon Reduction Era

We believe in "pursuing smart development, while also safeguarding our growing Earth, creating a beautiful future lifestyle."

Developing IoT Application Fields · Driving Green Benefits in Power Management
Strengthening R&D and Talent Core Capabilities · Providing Market Demand Solutions

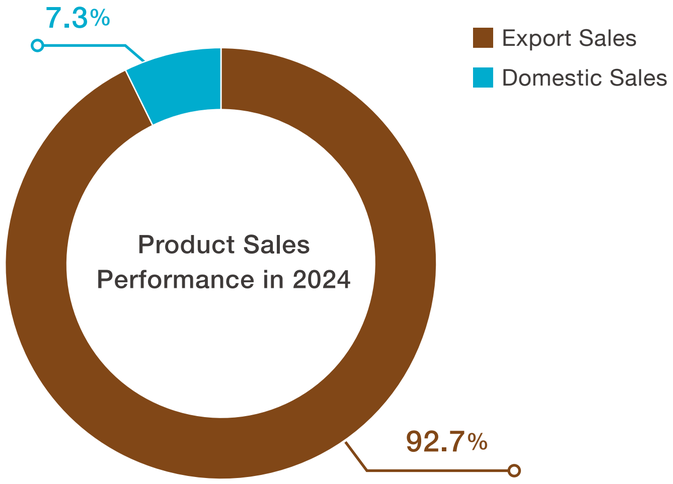
Fitipower is committed to developing various chips including display drivers and power management ICs. We will continue to consolidate R&D capabilities, developing diverse product applications and comprehensive one-stop services in edge computing, IoT, artificial intelligence, automotive electronics, and e-paper to rapidly meet the needs of various customers and potential customers. We aspire to promote smart and green living through human-machine interface innovation and five-senses interactive integration.



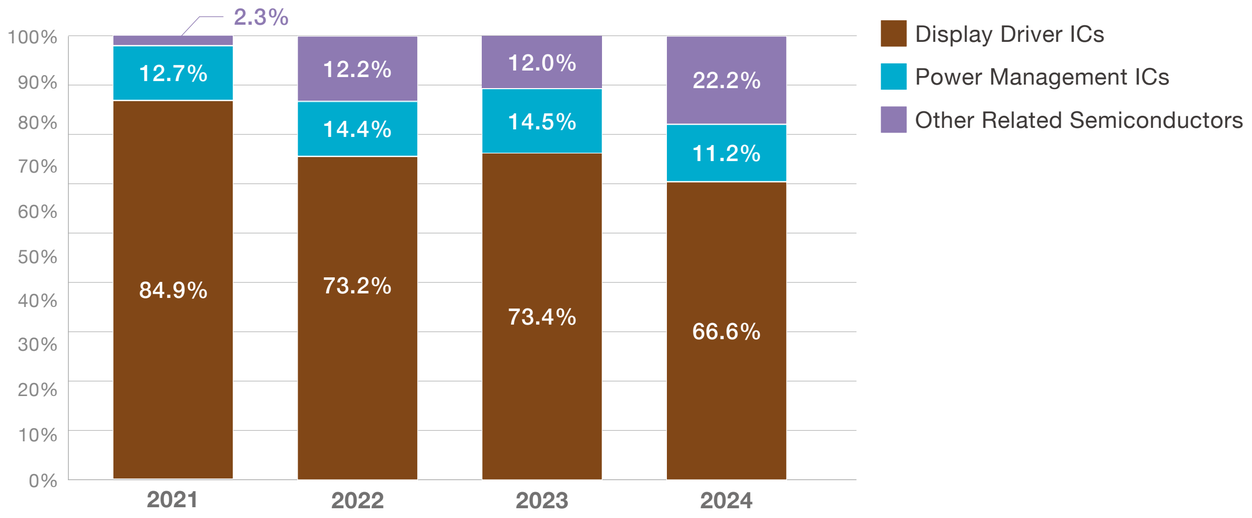
Customer-Oriented, Integrity & Accountability, Proactivity, Continuous Improvement, Communication & Coordination

We also expect colleagues to uphold five core values: "Customer-Oriented," "Integrity & Accountability," "Proactiveness," "Continuous Improvement," and "Communication & Coordination." Through communication, understanding and meeting customer expectations, acting responsibly and pragmatically, facing challenges directly, proactively taking action and continuously proposing improvements, we advance toward our common vision and mission.

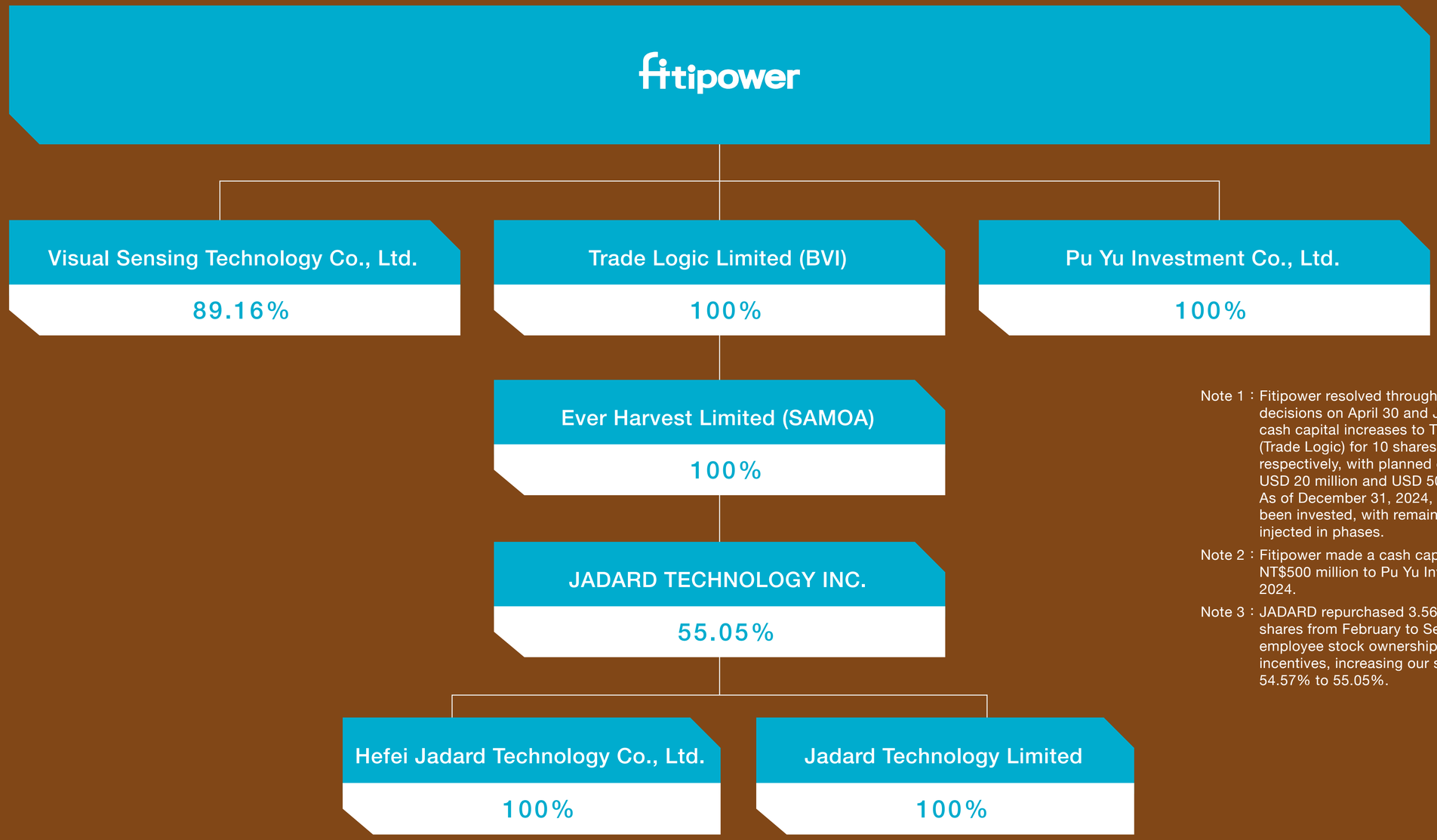
▶ Product Sales Performance in 2024



▶ Main Product Revenue



▶ Organizational Chart of Affiliates



Note 1：Fitipower resolved through Board of Directors' decisions on April 30 and July 24, 2024, to make cash capital increases to Trade Logic Limited (Trade Logic) for 10 shares and 25 shares respectively, with planned capital increases of USD 20 million and USD 50 million respectively. As of December 31, 2024, USD 46 million has been invested, with remaining funds to be injected in phases.

Note 2：Fitipower made a cash capital increase of NT$500 million to Pu Yu Investment in March 2024.

Note 3：JADARD repurchased 3.561 million treasury shares from February to September 2024 for employee stock ownership plans or equity incentives, increasing our shareholding from 54.57% to 55.05%.

1.2 Product and Technology Innovation

Goal — **Achieved**

Short-term Goals (2024-2026)

Display Driver ICs

- Mini/micro LED, AMOLED product applications
- Color e-paper technology product applications
- High-resolution, high refresh rate product applications
- Small-size driver IC product development for integrated systems
- High-integration panel power management IC product applications
- NB universal pgamma technology, flexibly adaptable to various panels

System on Chip (SoC)

- Develop high-quality, high refresh rate, low-power timing controller ICs
- Develop high-efficiency PMIC for color e-paper applications
- Develop micro LED PMIC for AR glasses applications

Power Management ICs

- Develop high-performance computing (HPC) applications
- DDR5 series PMIC development
- Develop compact, high-efficiency integrated converters

Sensor ICs

- Provide higher performance, lower power products for smart appliances/robot vacuums
- Develop low-power detection products for smart homes

HCITA

- Develop AI chips and applications supporting CNN-based and transformer architectures
- Develop AIoT-related edge AI applications

Other

- 12 new patent applications annually
- 2 industry-academia collaboration projects annually
- Digital optimization levels: 82%/84%/85%

Medium to Long-term Goals (2027-2030)

- Develop diverse product applications and comprehensive one-stop services for artificial intelligence (generative AI), edge computing, IoT, automotive electronics, and e-paper to rapidly meet various customer and potential customer needs
- Aspire to promote smart and green living through human-machine interface innovation and five-senses interactive integration
- 12 new patent applications annually
- 2 industry-academia collaboration projects annually
- TIPS/ISO 56005 certification
- 90% digital optimization level (2030)

Evaluation Indicators

- Product development and mass production
- Patent acquisition and protection

Responsibilities

- Employee
- Customer
- Academic Institution
- Association

Key Stakeholders

- R&D Unit
- IP Unit

Communication Mechanism

- Please refer to the “Key Stakeholders Communication Comparison Table” and match it with the key stakeholders mentioned above.

Driving the Evolution of Global Smart Living — *Drive* Your Heart

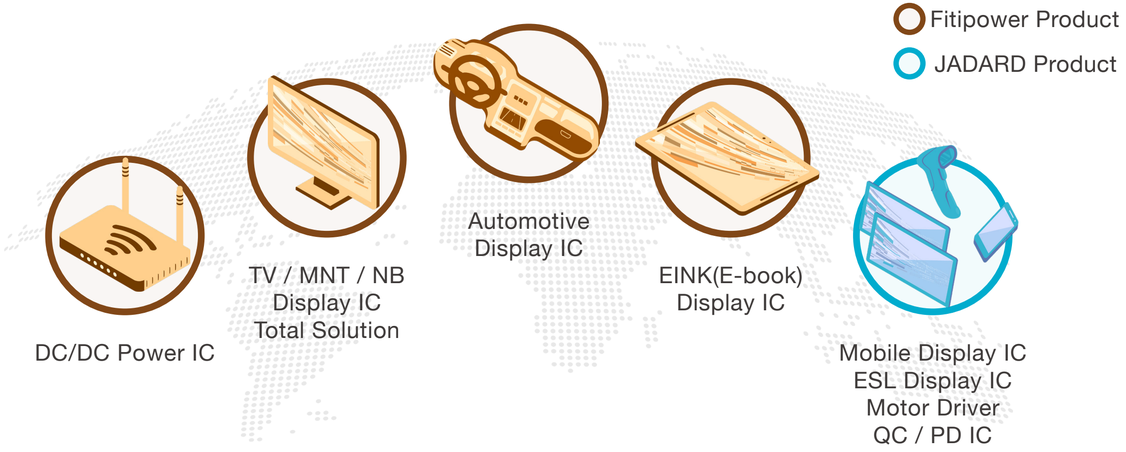
With the maturation and expansion of 5G technology, Internet of Things (IoT) application domains are expanding, bringing unprecedented breakthrough growth to display, sensing, and power control equipment markets. Facing future IoT human-machine interaction requirements for panel technologies—high resolution, diversified screen sizes, and growing experiential application demands—Fitipower has deeply cultivated the panel driver IC field. Our product end applications cover numerous domains including smartphones, smart wearable devices, smart retail, smart services, smart manufacturing, smart security, and digital homes, earning recognition and adoption from international industry leaders. As a leading enterprise in integrated driver single-chip R&D technology, we possess autonomous design capabilities. Combining years of technological accumulation and R&D investment while balancing company product development and industry connections, we collaborate with professional semiconductor manufacturing and packaging facilities to lead the artificial intelligence and IoT era, continuously pursuing human welfare through core product technologies.

Empowering Lower-Carbon and Energy-Efficient Global Smart Living — *Power* Your Life

Fitipower's main products in the power management IC field primarily include switching regulator ICs, linear regulator ICs, and power management integrated components, widely applied in desktop/laptop computers, smartphones, smart TVs, set-top boxes, network communication equipment, and security monitoring equipment. In 2007, our company pioneered Taiwan's first 600V high-voltage white light-emitting diode (WLED) driver IC and became one of the major suppliers of power solutions for laptop computers, LCD TV components, and network device ICs. As environmental consciousness receives increasing attention, power usage efficiency in electronic products has become an actively improved priority. We actively develop high-performance power management ICs for various electronic product applications, hoping to balance power supply growth with environmental protection while fully supporting government energy conservation policies. Subsequently, we will also develop high-voltage, high-current, and high-reliability product lines targeting electric vehicle development trends.

Product Applications and Leading Technologies

Fitipower has deeply cultivated panel display IC and power management IC fields, with product end applications covering smart home TVs, high-end commercial computer monitors, laptop computers, and extensive power management IC domains. Product types include display driver ICs, timing control and power management ICs, and network device power management ICs. Looking forward, we will commit to expanding low-power smart IoT (AIoT) and high-performance electric vehicle-related IC products.



▶ R&D Achievements in 2024

R&D Achievement	Application Field
Low-power eDP 1.5 Timing Control	Laptop panels
VividX Next-generation Color Processing eDP 1.2 Timing Control	Laptop panels
Color E-paper Power Management IC	E-readers
Ultra-large Display UD 165Hz High Refresh Rate Timing Controller IC Development	TV panels
FHD/QHD High Refresh Low Heat Driver IC	Surveillance monitor panels
High PSRR LDO, effectively reducing power noise impact on images and improving image quality	Smartphone CCM/AR/VR applications
Front Light LED Driver IC	E-readers
High Performance BLDC MCU Mass Production and Shipment	High-speed hair dryers
New COT Low Vin Buck 1A/2A/3A	Networking, smartphones, TVs
Low Iq Boost converter	Remote controls, mice, keyboards

Comprehensive Display Panel IC Solutions

As AI computing accelerates integration into personal computers and mobile devices, consumer demand for high-performance, high-resolution, low-power 3C products continues rising, driving brand manufacturers to actively launch innovative products to promote market upgrades. Smart display technologies, high refresh rates, HDR, Variable Refresh Rate (VRR), and AI image enhancement have become key market development trends. Fitipower provides customers with comprehensive solutions for various panel driver ICs and commits to developing multi-IC energy-saving solutions to optimize end-product power consumption, achieving a balance between high performance and low energy consumption to meet market demands for smart display technology.

- Industry-leading complete solutions for ENERGY STAR 8.0 and 9.0 mass production
- Low-voltage, high-frequency, low-power driver IC mass production for monitors, and FHD dual gate/L-driver low-power, high-integration complete solution development for laptops
- TV driver IC supporting tri-gate complete solutions, and P2P high-speed interface direct connection to SoC supporting Tconless design, reducing chip count per LCD TV
- TV and monitor driver ICs supporting low-power heat sink-free solutions, reducing power consumption and simplifying thermal design
- Small and medium-sized AV products corresponding to WVGA, WSVGA, WXGA, FHD resolutions all have single driver solutions, and 4K resolution provides solutions requiring only two drivers, reducing chip count for small and medium-sized panels
- AMOLED smartphone driver ICs [Note 1] with built-in power, logic, and output circuit noise reduction design effectively improve image quality; simultaneously supporting multiple compensation algorithms for panel defect voltage and uniformity compensation, including data line coupling compensation and pixel drive voltage adjustment, ensuring display consistency and stability

Note 1：AMOLED smartphone driver ICs are products of subsidiary JADARD

E-Book Display Driver Chips

Fitipower is a major global supplier of e-paper driver chips. E-paper technology offers significant energy and environmental benefits due to its paper-like display effects, reduced eye fatigue reading, and zero power consumption for static images, widely applied in e-book readers, notebooks, and electronic tags. The rise of remote education has driven overall e-paper reader demand growth. In response to market trends toward larger and colorized display screens, development has expanded from mainstream 6-inch to comprehensive sizes including 10.3-inch and even 13.3-inch, with color e-paper chip development. These changes drive our efforts to reduce required driving voltage while maintaining page-turning speed, achieving more environmentally friendly and power-saving designs.

- Zero power consumption display characteristics for static images with fast power-up/down design
- Industry-first multi-power switching color e-book driver chip
- Industry-first low-power multi-power switching cost-reduction four-color display driver chip
- Industry-first 7-level voltage driving technology providing contrast and detail far exceeding 2-bit, presenting clear text and vivid images

Various Power Management ICs [Note 2]

Fitipower develops high-performance LDO and power management IC solutions for laptop, camera, smartphone CCM, AR, and VR markets. LDO products feature low-noise characteristics, effectively reducing power interference with image quality, and adopt compact WLCSP packaging to meet modern equipment demands for high performance and miniaturization. Additionally, power ICs use BCD processes integrating MOS switches, mixed signals, and analog components, maintaining high efficiency even under light loads, supporting 100% duty cycle operation, achieving low dropout operation, helping customers reduce energy consumption and costs, and improving end-product energy efficiency and system stability.

- Reduced output noise, improved output stability and high power supply rejection ratio (PSRR)
- Ultra-low quiescent current, power-saving mode and deep sleep mode, reducing power consumption and extending battery life
- Dynamic voltage regulation adjusts power voltage based on actual system usage; reducing power voltage during system idle or low-speed operation significantly reduces circuit power consumption
- High operating frequency enables smaller inductor components, reducing circuit board area, high integration and internal compensation circuits save more external components (MOS switches, compensation capacitors, etc.)
- Comprehensive range of products for high-voltage automotive power, HPC high-current requirements, and multi-phase high-wattage power applications, plus optimal design solutions for next-generation color e-ink displays

Note 2：Including DC/DC buck and boost ICs, low dropout linear regulators, USB power switches, LED drivers, brushless DC motor drivers, e-paper power management ICs

Electronic Label Display Driver Chips[Note 1]

With smart retail development, online-offline integration and real-time information synchronization have become core retail industry needs. Electronic Shelf Labels (ESL), due to their low-power characteristics, are widely applied in IoT, edge computing, and logistics fields, significantly reducing energy and resource waste and promoting rapid demand growth. We provide complete solutions from 1.54 to 3.5 inches and actively develop new products integrating energy harvesting technology, promoting battery-free, consumable-free sustainable product development.

- Pioneering anti-fragment detection and active feedback mechanism providing real-time label damage alerts to merchants, reducing manual inspection costs
- Industry-leading sub-3-inch high-resolution driver IC significantly improving display effects and customer satisfaction
- Cutting-edge development of driver ICs integrating energy harvesting technology for battery-free applications
- Industry-first mass production four-color electronic label driver chip with six-color version under development
- AI technology development for electronic label automatic waveform adjustment technology; upon maturity, significantly reduces manpower and time for electronic label mass production preparation
- AI technology introduction for electronic label color correction functions, reducing inter-chip color differences
- VividInk ™ Scoring technology development using AI to automatically select dithering effects most aligned with human visual aesthetics

Note 1： Electronic labels are products of subsidiary JADARD

AI Application Chips

Fitipower's development roadmap targets AI algorithm and hardware co-design and co-optimization, focusing on TinyML applications and markets. To master TinyML key technologies, Fitipower has engaged ITRI and Cadence for TVM and System C technology training and guidance in recent years. In 2021, we successfully developed a TVM NN Compiler prototype design solution In 2022, we successfully developed a low-power multi-core architecture general-purpose AI accelerator (supporting CNN neural networks primarily). In 2025, AI chips are progressively being sampled to AIoT customers.

- Lightweight AI models: Optimizing AI models for specific application scenarios (such as voice recognition, environmental sensing) to reduce computational complexity
- Hardware acceleration: AI accelerators improving computational efficiency while reducing power consumption
- Low-cost implementation: Application-specific ICs optimizing key functions without pursuing excessive additional features, significantly reducing costs
- Self-developed IP: Leveraging existing IP modules for self-design or optimization, saving IC area while mastering key technologies for continuous evolution

Sensor Chips

Fitipower utilizes laser light sources and CMOS sensing technology to develop high-performance laser ranging modules, overcoming traditional infrared sensor limitations of environmental light and target color interference and inability to measure distance accurately. Through precise energy and activation time control, power consumption is significantly reduced, extending sensor battery life from weeks to years. This module achieves high-precision ranging within 5% under average power consumption lower than infrared sensors, suitable for faucet, toilet water sensing, and foot kick switch applications. Additionally, customers can utilize ranging functions for advanced controls like smart water volume and temperature management, achieving more energy-efficient smart living.

Research & Development and Patents

Facing rapid technological advancement and changing market demands, Fitipower continuously accumulates R&D capabilities based on existing comprehensive technology, consistently providing customers with comprehensive design services and products. In 2024, Fitipower Group had 232 R&D personnel with total R&D investment of NT$2.494 billion, representing 13.0% of total revenue. Additionally, to incentivize patent development, we established "Procedures for Patent Proposal Incentive." In 2024, 22 new patents were approved (Fitipower: 14; JADARD: 8). Cumulatively through the reporting period end, Fitipower Group holds 154 valid domestic and international patents. Fitipower will continue expanding patent portfolios, increasing R&D investment and encouraging patent creation to protect Fitipower's R&D achievements and intellectual property rights. We will also continue actively participating in industry-academia organizations, promoting semiconductor industry cooperation and healthy industry system development.

Fitipower's driver ICs are primarily applied in large display systems (laptops, monitors, and TVs). These systems use multi-chip discrete architectures requiring processing of multi-chip driver IC data reception synchronization to achieve correct sectioned pixel capacitance data, while considering similar driving voltage capabilities between different ICs at connection points to ensure consistent display performance [Note 1]. Additionally, inter-system IC compatibility is a key design consideration, as different manufacturers and specification transmission interfaces show different signal integrity performance in various size applications, requiring appropriate circuit compensation techniques for complete data reception and diverse compatibility applications. For power management ICs, primarily targeting networking and 3C markets, recent products pursue high efficiency, low standby power consumption, and energy-saving oriented new product series; also developing high-voltage, high-current, and high-reliability product lines targeting electric vehicle development trends.

Fitipower Intellectual Property Management Plan and Implementation in 2024

Display Driver ICs		Power Management ICs	
• Multi-chip discrete architecture • Inter-system IC compatibility		• High-voltage constant on-time buck architecture • Multi-phase high-current buck architecture	
Computers and monitors	TVs	Network communication devices	Electric vehicles
• Low power consumption • Anti-noise (GSM noise) and reduced noise emission (Touch noise) [Note 2]	• Larger sizes • High resolution (8K/4K) • High refresh rates • Enhanced buffer driving capability and narrow bezel applications [Note 3] • Improved transmission interface speeds [Note 4] • Electric vehicles	• Compact size • High efficiency • Low power consumption • High integration	• High voltage • High current • High reliability

Note 1：Circuit technologies include multi-drop/P2P data transmission interfaces, high-strength gamma buffers, offset cancellation to reduce channel buffer deviation, sectored time-division driving, and gamma string layout symmetry optimization.

Note 2：Circuit technologies include charge recycle, dynamic on/off switching, high PSRR bandgap LDO circuits, differential mode noise suppression, and dynamic signal swing adjustment.

Note 3：Circuit technologies for enhanced driving capability and narrow bezel applications include output impedance reduction technology, fast gamma charging, fan-out compensation (FOC), and gate delay compensation (GDC).

Note 4：Transmission interface circuit technologies include adaptive EQ, offset calibration, automatic frequency band selection, and high PSRR LDO to enhance interface anti-noise interference capability.

▶ New Patents Obtained in 2024 (Fitipower)

Patent No.	Name	Description
TWM650145U	Chip Package and Lens Module	Provides a chip package and lens module, where the chip package includes a package body and multiple solder points. The package body includes a mounting surface with multiple solder points disposed thereon. At least one of the solder points has a mounting axis, with asymmetric shape relative to the mounting axis, and the mounting axis forms a specific angle with the first direction of the package body. This application improves product yield and production efficiency by changing solder point shapes and positioning angles on chip packages, making the mounting surface directionally identifiable to avoid incorrect orientation during processing and production.
TWI831526B	Bandgap Reference Circuit and Method for Simultaneously Generating Reference Voltage and Reference Current	Provides a bandgap reference circuit including: common circuit, current compensation circuit, voltage lock circuit, and current mirror circuit. The common circuit includes a first resistor, second resistor, and first transistor connected in series from an output terminal for outputting reference voltage. The current mirror circuit's first branch connects to the output terminal to provide parallel current, while the second branch outputs reference current. The current compensation circuit ensures the current generated has opposite temperature coefficient to the common circuit current; the voltage lock circuit ensures the voltage difference across the second resistor has opposite temperature coefficient to the first transistor's emitter voltage. This case also provides a method for simultaneously generating reference voltage and reference current.
CN112036325B	Fingerprint Recognition Module and Display Device	A fingerprint recognition module for under-display fingerprint recognition, including optical sensor module, at least two light-emitting elements, at least two first polarizers, second polarizer, and at least two polarization rotators. Each light-emitting element is positioned around the optical sensor module periphery. The optical sensor module collects light emitted by light-emitting elements and reflected by fingers to form fingerprint images. Each light-emitting element's light exit surface has a first polarizer. The second polarizer faces the optical sensor module on the side where it acquires fingerprint optical signals, with first and second polarizer axes perpendicular to each other. Polarization rotators are positioned opposite each first polarizer on the side away from light-emitting elements, rotating polarized light from first polarizers to change polarization states. This invention also provides a display device applying the fingerprint recognition module.
TWD230851S	Chip Package	This design's key point lies in the product's overall appearance and shape. The chip package design includes a package body and multiple solder points disposed on the package body's mounting surface. The design's characteristic feature is solder points with asymmetric shapes composed of curved and straight edges (as shown in front view) with specific positioning angles, creating an overall appearance with distinctive visual effects.
CN112530338B	Amplifier Circuit	This invention provides an amplifier circuit including: input amplifier module with first and second output terminals; output amplifier module with first input terminal, second input terminal, and output terminal; and overshoot suppression module electrically connected to the input amplifier module's first and second output terminals, output amplifier module's first and second input terminals and input terminal, controlling voltages within preset ranges based on output amplifier module output voltage and stacked bias circuit voltage. The overshoot suppression module includes stacked bias circuit and wide-swing clamp circuit, with the wide-swing clamp circuit electrically connected to both ends of the stacked bias circuit. The bias circuit receives bias signals, while the wide-swing clamp circuit controls the overshoot suppression module's conductive or open circuit state based on bias signals and output amplifier module output signals.
US11972587B2	Method for Establishing Semantic Distance Map and Related Moving device	An establishing method of semantic distance map for a moving device, includes capturing an image; obtaining a single-point distance measurement result of the image; performing recognition for the image to obtain a recognition result of each obstacle in the image; and determining a semantic distance map corresponding to the image according to the image, the single-point distance measurement result and the recognition result of each obstacle of in the image; wherein each pixel of the semantic distance map includes an obstacle information, which includes a distance between the moving device and an obstacle, a type of the obstacle, and a recognition probability of the obstacle.
CN112201189B	Level Shift Circuit and Display Device with Level Shift Circuit	A level shift circuit and display device including differential input circuit, current limiting circuit, latch circuit, and voltage shielding circuit. The voltage shielding circuit includes first through fourth shielding transistors. First and second shielding transistors are connected in series between the differential input circuit and second output terminal, while third and fourth shielding transistors are connected in series between the differential input circuit and first output terminal. First and third shielding transistor gates receive first voltage, while second and fourth shielding transistor gates receive second voltage lower than the first voltage. First and third shielding transistor substrates receive third voltage, while second and fourth shielding transistor substrates receive fourth voltage higher than the third voltage.
CN221008939U	Chip Package and Lens Module	Provides a chip package and lens module, where the chip package includes a package body and multiple solder points. The package body includes a mounting surface with multiple solder points disposed thereon. At least one of the solder points has a mounting axis, with asymmetric shape relative to the mounting axis, and the mounting axis forms a specific angle with the first direction of the package body. This application improves product yield and production efficiency by changing solder point shapes and positioning angles on chip packages, making the mounting surface directionally identifiable to avoid incorrect orientation during processing and production.
CN308669802S	Chip Package Solder Points	1.This industrial design product name: Chip package solder points.
TWD231747S	Chip Package Solder Points	2.This industrial design product application: Chip packages and chip package solder points applied to semiconductor components
TWI846510B	Voltage Conversion Circuit, Control Method, and Voltage Conversion System	3.This industrial design product's design key point: The shape and spatial distribution of chip package solder points.
TWI847587B	Test Program Development Method, System and Electronic Equipment	This design's key point lies in the shape and spatial distribution of chip package solder points.
KR30-1271144-0004	칩 패키지 CHIP PACKAGE	The combination of "chip package" shape and form is the key point of design creation content.
KR30-1273393-0001	칩 패키지 CHIP PACKAGE	The combination of "chip package" shape and form is the key point of design creation content.

Note：For JADARD patent details, please refer to the "JADARD 2024 Sustainability Report."

Digital Transformation and Automation Competition

Facing the rapid advancement of digital technology, we conducted a company-wide digital optimization inventory in 2022, comprehensively evaluating each department's operations and encouraging colleagues to propose appropriate digital initiatives for their work. By the end of 2024, our overall digitalization level reached 86%, with 75 work items identified for further enhancement and planning. In response to AI transformation trends in 2024, the Company planned to establish an AI platform integrating various daily operations to provide rapid solutions and real-time responses to external user feedback.

We improve internal organizational management processes and costs while enhancing work efficiency and ensuring quality management. Fitipower regularly hosts the "Golden Opening Awards," encouraging colleagues to develop automation concepts from their responsible operations and projects. From conceptualization, proposal, execution to widespread application as cross-departmental benchmarks, the competition is divided into "Design," "Office Automation," and "Verification & Engineering" categories and has been held for six consecutive years. In 2024, we organized 4 sessions (2 sessions for Verification & Production), with a total of 48 participating teams, 19 award-winning projects, and total prize money of NT$580,000.

▶ Award-Winning Projects in 2024

Category	Award	Project Name	
Design	Champion	• AI-Assisted Automated IP Design Language Conversion (Verilog to C)	
	Distinctive	• CI/CD Fully Automated Development Platform	
Validation and Production	Champion	• STD cell Re-K Library • One-Click, Highly Integrated Universal Power IC Verification Platform	• EMI Near-Field Measurement Automation Platform Development • Auto-generation of LEF & DEF for APR
	Distinctive	• All-in-one Closed Loop/OIS VCM Adjustment Automation • TCON Systematic Fast Verification V2.0 (Module FT) • Automatic Generate Initial code for TDDI IC • Neural Network Database Construction QFN Prediction Platform • JDTool Sensor Mapping • Multi-Platform Data Analysis System • Panel Power Level Shifter IC Input Verification Automation	• Neural Network Database Construction SPICE MODEL Behavior Prediction Platform • AI Auto ESL Font Sharpness Tuning • FRC Image Quality Automated AI Recognition System
Office	Champion	• Organizational Chart of the Group's Chain of Command	
	Distinctive	• Issue Tracking System • Last Time Buy One-Stop Shop	